

PROCESS AND APPARATUS FOR DISENGAGING SEMICONDUCTOR DIE FROM AN ADHESIVE FILM

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ABSTRACT OF THE DISCLOSURE

20251120 08344007

An apparatus and method for separating a semiconductor die (303) from an adhesive tape (32) are disclosed. The apparatus includes a blade (34) mechanically coupled to a blade holder (36), wherein the blade (34) is inclined relative to the primary surface of the semiconductor die (303). The method further comprises lifting the semiconductor die (303) while it is attached to the adhesive tape (32) to assist disengagement. The blade (34) facilitates peeling of the semiconductor die (303) from the adhesive tape (32) while distributing stress exerted on the semiconductor die (303) over a larger surface area resulting in reduced die fractures (20).

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